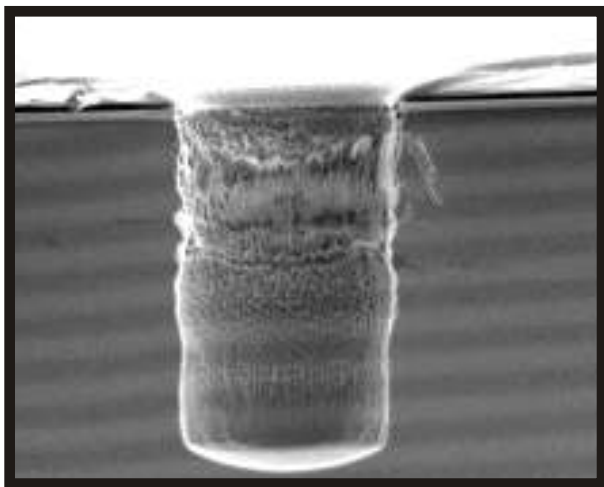


# Plasmalab Data

## InP Via Hole RIE Etching



OPT application lab:  
100 µm deep via hole etched in InP

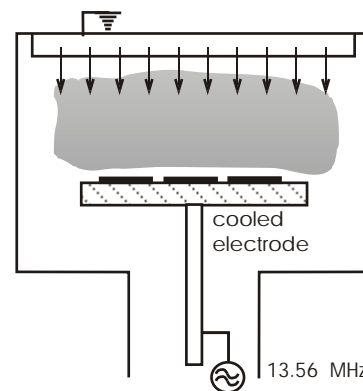


*Plasmalab System 133*

*Plasmalab System 100*



*Plasmalab 80 Plus*



**Technology:**

- RIE-Mode: 13.56 MHz
- Shower Head Gas Inlet
- BCl<sub>3</sub> and HBr based process

**Results:**

- rate > 2.5µm/ min
- uniformity < +/- 5% (3" wafer)
- selectivity > 15:1 to PR
- profile: anisotropic (or shaped)